

Approval Sheet

Products	Dielectric Chip Antenna		
Customer	UTstarcom		
Model		GTX-75	
Customer CODE			
Supplier		PARTRON	
Supplier CODE		ACS2450ICAKNB	
	By designed	By checked	By approved
UTstarcom			
	By designed	By checked	By approved
PARTRON	12(6)	String	例从
	Research 5 Team	Quality Assurance	Laboratory
	Chanik.Jeon	Nam-Sik.Min	Byoung-Jun.Yim
	04/23	04/23	04/23

2008. 04. 23



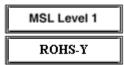
22-6 Seokwoo-dong, Hwaseong-si, Gyeonggi-do, Korea 455-300

Tel: 82-31-201-7870~6 Fax: 82-31-201-7800 www.partron.co.kr

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SPECIFICATION

MODEL: ACS2450ICAKNB

3D Structure				
*KNB84				
Top View Bottom View		tom View		
By designed	By checked	By approved		
with	Strike	例从		
Research 5 Team	Quality Assurance	Laboratory		
Chanik.Jeon	Nam-Sik.Min	Byoung-Jun.Yim		
04/23	04/23	04/23		

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1. Revision

Revision No	Originator	Description of changes	Date of changes
Ver 1.0	Chanik.Jeon	Issued	2008.04.23

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2. Summary of Parts

- This product is the internal dielectric chip antenna of radio communication, forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

Туре	Only Bulk Ceramic		
Material	Dielectric Block	Mg₂SiO₄(Magnesium Silicate)	
Material	Electrode Paste	Ag	
	$W = 3.0\pm0.1$		
Size[mm]	$L = 9.0\pm0.1$	Ag Paste	
T = 1.2±0.1		W	
Flatness Level	0.04	T	
MSL Level	MSL Level 1		
ESD Level	More than 15 KV (HBM CLASS 3B)	Top-Side View Dielectric Block Bottom-Side View	
Version	Revision 1.0		

3. Critical to Quality (

- The following list is specified as the emphasis management list and managed.

CTQ ITEM	Specification Reason	
Shape weight, size	Shape weight and size determines the electric block size after plastic and the dielectric block size effects the level of detail for the printing.	
Plastic Size	The size after plastic effects the level of detail for the printing.	
Printing Size	The level of detail for printing size is an essential list of the BT antenna.	

CTF ITEM 📀	Specification Reason
Single Element measurement SWR	An important Parameter classifying the electrical characteristics.

- require attention for the following list.

ITEM	Content	
Keeping	Sealing tightly when keeping for a long time.	
Action	Maybe characteristics changes when changing any design.	

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4. Electrical Characteristics

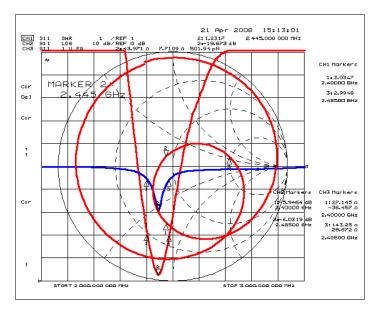
4.1 Set Condition

ITEM				SPEC
Frequency Range [MHz]			2400 ~ 2485	
	SWR	[Max]		3.5 : 1 (Typ 3.0 : 1)
	Input Impe	dance $[\Omega]$		50 Ohm
	Polariz	ation		Linear
	Total Gair	n (Peak / /	Avg) [dBi]	0.5 / -7.1
		T I	Peak	-4.22
	Azimuth	Theta	Average	-9.96
		Phi	Peak	-1.48
			Average	-7.87
			Peak	0.50
Gain[dBi]	Elevation 1		Average	-4.18
			Peak	-2.19
		Phi	Average	-8.96
	Elevation 2	Theta	Peak	-4.75
			Average	-9.79
		Phi	Peak	-0.28
			Average	-5.25

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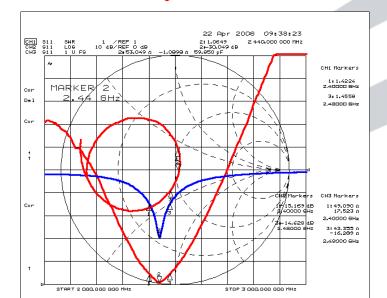
4.2 S11 Graph of Set Condition



4.3 Test Fixture Condition

ITEM	SPEC
Frequency Range [MHz]	2400 ~ 2480
Lower frequency(2400MHz) SWR [Min~Max]	1.0 ~ 3.0 : 1 (Typ 2.5 : 1)
Upper frequency(2480MHz) SWR [Min~Max]	1.0 ~ 3.0 : 1 (Typ 2.5 : 1)

4.4 S11 Graph of Test Fixture Condition CTD

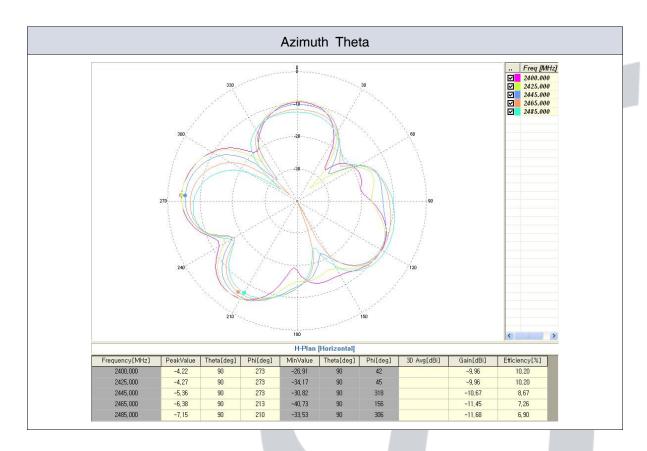


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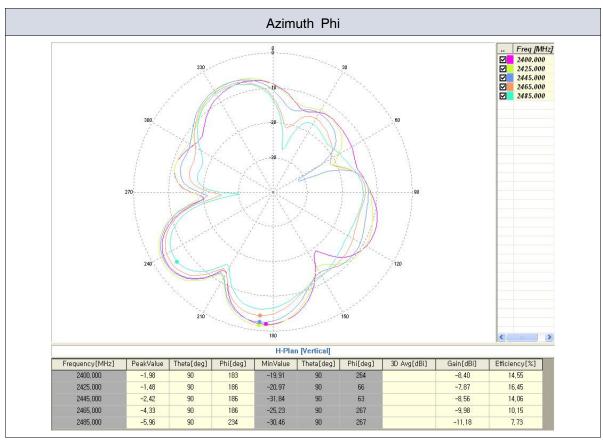
4.5 Radiation Pattern

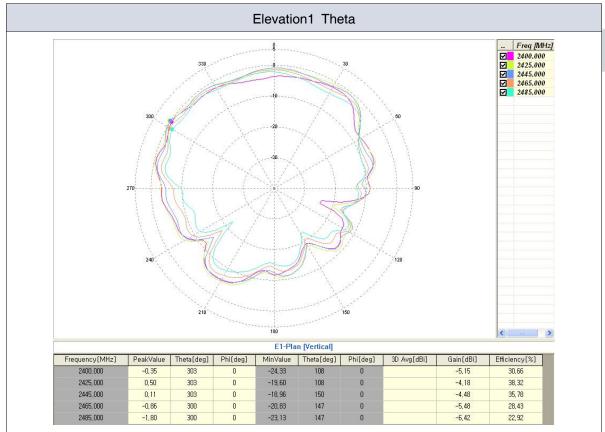
Azimuth Plane	Elevation1 Plane	Elevation2 Plane
270° 90°	90° 180°	270° — 90° — 90° — 180°
Theta	Vertical field of measured plane	
Phi	Horizontal field of measured plane	



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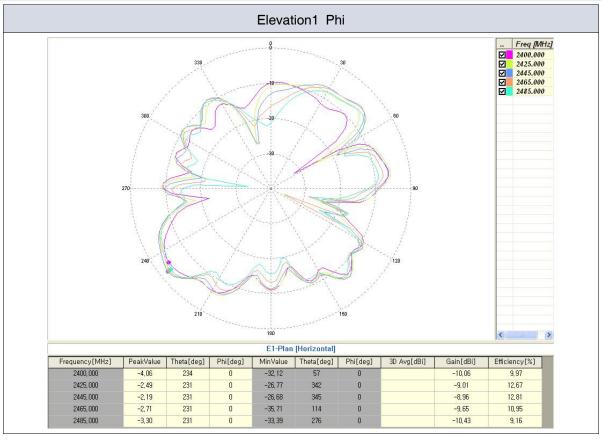


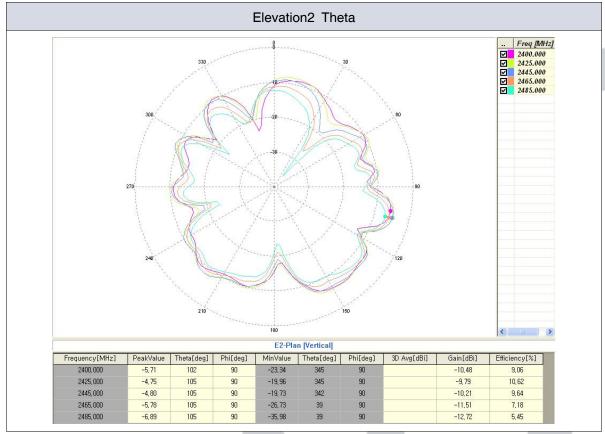




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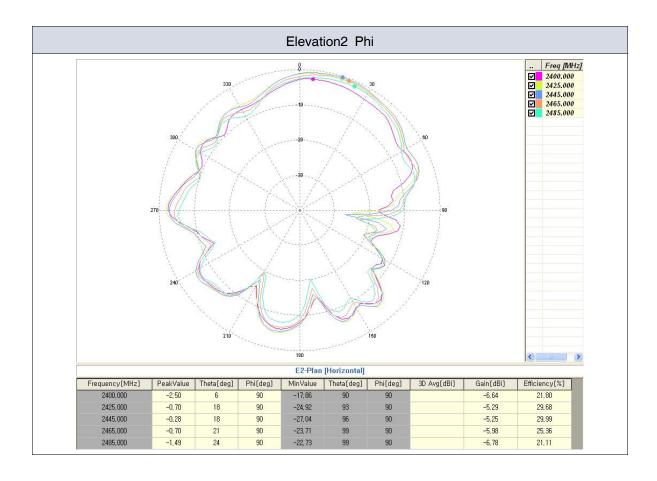






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5. Measurement Process

5.1 SWR/Return loss

Use Network Analyzer when measuring SWR/Return loss and selecting standard SPL, Use automatic inspection equipment when selecting superior and inferior goods.

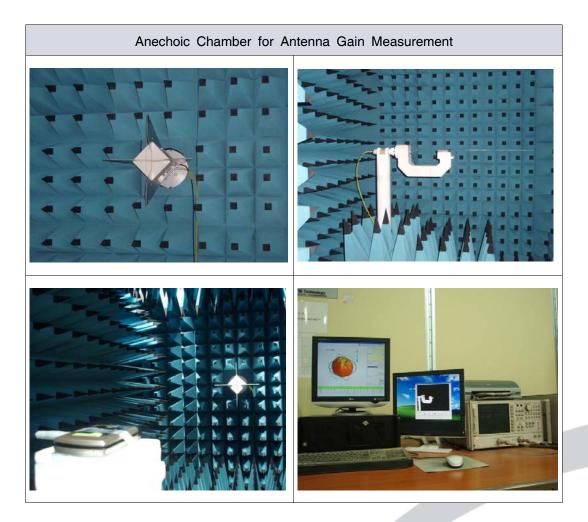
	Set Condition	Test Fixture Condition
Network Analyzer	Agilent HP8753D	Agilent HP8753D or Advantest R3765CH
Cable	RF cable(300mm)	RF cable(300mm)
Test condition		CLUB CLUB CLUB CLUB CLUB CLUB CLUB CLUB

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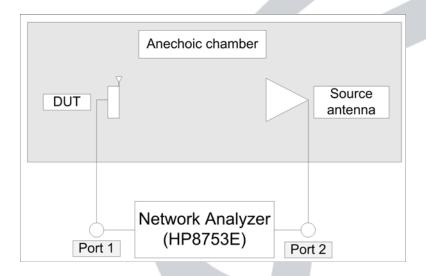


5.2 Gain

Antenna gain is measured in the Anechoic Chamber of this company, using set above of 4.1 list.



5.3 Gain test block diagram

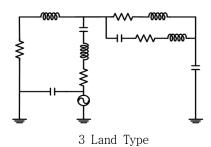


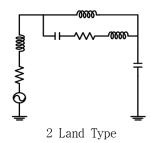
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6. Internal Block Diagram

This product is made of the dielectric block and RF part materialized the characteristics by structural change of Ag pattern on the brick of dielectric block and conditioning value of the structural equivalent circuit.

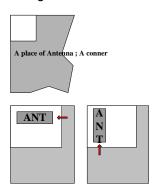




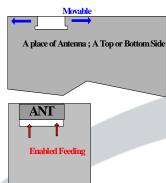
7. Basis Action / Application Note

This product is the internal dielectric chip antenna of radio communication, coverts the electric signal advanced along by transmission line into free space wave.

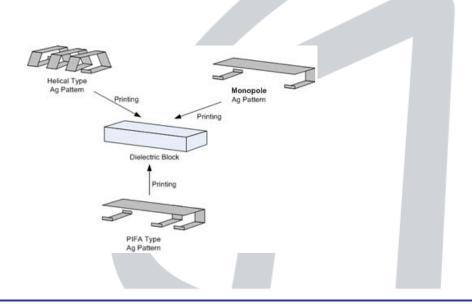
This product will be mounted wherever you want and the design is revised by mount condition. But require attention to select the mount position, because this product is the radiation part and changed characteristics by boundary condition,







As the following, this product is easy to revise the various types for the boundary condition.



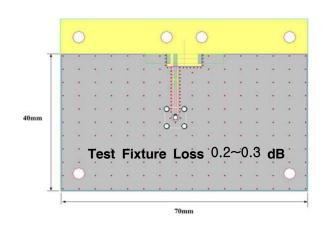
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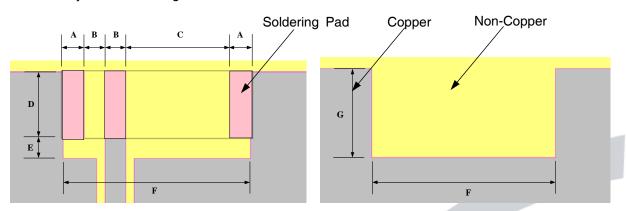
8. Measurement Jig SPEC

8.1 Test Fixture And GROUND Condition





- Ev B'd and Test Fixture Jig is the same
 (Contact way of Ev B'd is soldering, Test Fixture is copper contact way)
- 8.2 PCB Layout & Soldering Pad Dimension



Top Lavout

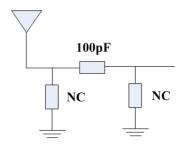
-1							
Parameter	Α	В	С	D	E	F	G
Value[mm]	1.1	1.0	5.0	3.2	1.0	9.0	4.0

Unit; mm

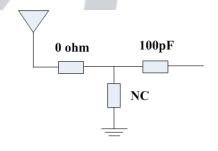
Bottom Pattern

Unless specified tolerances are ±0.1

8.3 Matching Circuit And Reference Value



π Matching



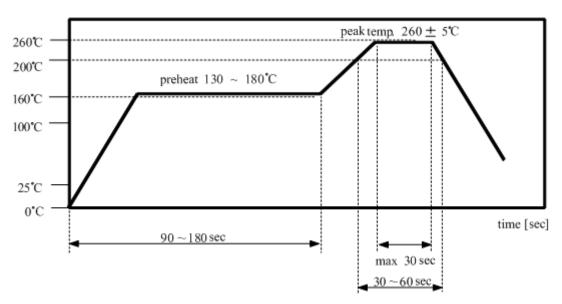
T Matching

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9. REFLOW PROFILE

9.1 Reflow Soldering

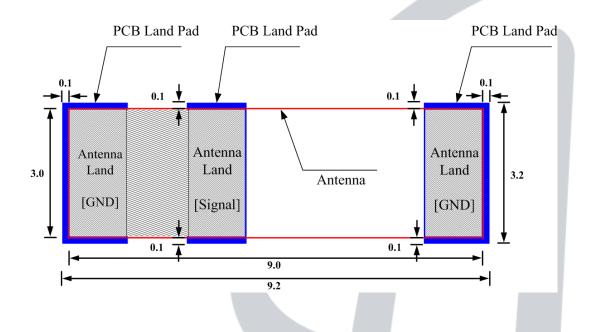


9.2 Manual Soldering

Soldering Temperature : $340\,^{\circ}\text{C}\,\pm5\,^{\circ}\text{C}$, 5sec max per each terminal

9.3 PCB Pattern Design

As the following, the PCB land pattern lays out 0.1mm outside land pattern of antenna more than indicated antenna land dimension



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10. Primary Inspection List

Item	Electrical Characteristic[MHz]			Size [mm]	
	VSWR 3.	0:1 MAX	W 00 04		T=1.2±0.1
Standard	2400MHz	2480MHz	W=3.0±0.1	L=9.0±0.1	
1	1.39	1.40	3.01	9.00	1.21
2	1.40	1.40	3.01	9.01	1.21
3	1.49	1.32	3.01	9.01	1.21
4	1.42	1.36	3.03	9.00	1.20
5	1.36	1.42	3.01	8.99	1.21
6	1.43	1.33	3.02	8.99	1.20
7	1.32	1.40	3.01	9.01	1.22
8	1.47	1.29	3.01	9.03	1.21
9	1.38	1.34	3.00	9.02	1.23
10	1.41	1.39	3.01	9.01	1.21
11	1.38	1.45	3.02	9.01	1.22
12	1.41	1.40	3.01	9.00	1.21
13	1.34	1.42	3.02	9.01	1.21
14	1.42	1.35	3.02	9.03	1.21
15	1.42	1.37	3.01	9.03	1.20
16	1.32	1.44	3.01	9.01	1.21
17	1.37	1.43	3.01	9.00	1.21
18	1.46	1.36	3.00	8.99	1.20
19	1.37	1.43	3.01	9.02	1.22
20	1.38	1.39	3.01	9.01	1.21
Min	1.32	1.29	3.00	8.99	1.20
Max	1.49	1.45	3.03	9.03	1.23
Х	1.39	1.38	3.01	9.01	1.21
σ	0.05	0.04	0.01	0.01	0.01
Cpk	2.85	2.92	4.16	2.39	3.88
Decision	ОК	OK	ОК	ОК	OK

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11. Reliability Condition

11.1 Environment Test

ITEM	TEST CONDITION	LIMIT	
High Temperature Action	85℃±3℃, 1hr		
High Temperature Resistance	+85℃±3℃, 120hr±2hr		
Low Temperature Action	-40℃±3℃, 1hr	After test, Must meet the	
Low Temperature Resistance	-40℃±3℃, 120hr±2hr	characteristics spec of 4.4 list	
Humidity Action	+85±3℃, RH85%		
Humidity Resistance	+85±3℃, RH85%, 120hr±2hr		

11.2 Thermal shock test, Reflow test

ITEM	TEST CONDITION	LIMIT
	condition : -40 $^{\circ}$ ±3 $^{\circ}$ /1min \leftrightarrow +85 $^{\circ}$ ±3 $^{\circ}$ /1min	
Thermal shock	Test Cycle: 32 cycle	After test, Must meet the
	Temperature change time: within 5 min	characteristics spec of
Reflow	Pre Heating: 200±5℃, 30~60 sec	4.4 list
Hellow	Peak Heating: 260°C±5°C, 30sec Max	

11.3 Mechanical Test

ITEM	TEST CONDITION	LIMIT	
Vibration	Freq : 10~500Hz , Acceleration : 10 $\times 9.8$ % (G)		
Vibration	Sweep time: 15 min, X.Y.Z each 5 times	After test, Must meet the	
	18 times free fall Using the drop jig 152cm high	characteristics spec of	
Drop	Jig: 120g±20g Plastic Jig	4.4 list	
	Bottom : Concrete or Iron		

11.4 MSL LEVEL Test

1) JEDEC J-STD-020C Test

	F	Floor Life	Soak Requirements	
	Time	Conditions	Time	Conditions
1	Unlimited	= < 30°C/85%RH	168+5/-0	= < 85°C/85%RH

2) Test Condition

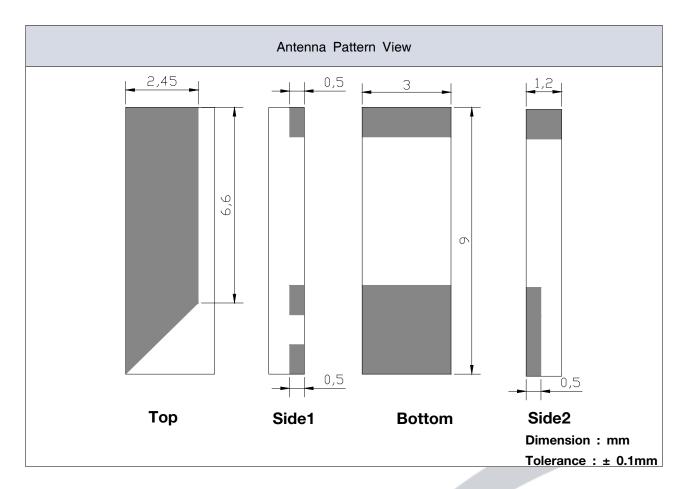
ITEM	Conditon		LIMIT
Soak Requirements	After leaving +85±3℃, RH85% 2 times Reflow without aging	168hr±2hr	After test, Must meet the characteristics spec of 4.4 list

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12. Mechanical Characteristics

12.1 Antenna Pattern Dimension





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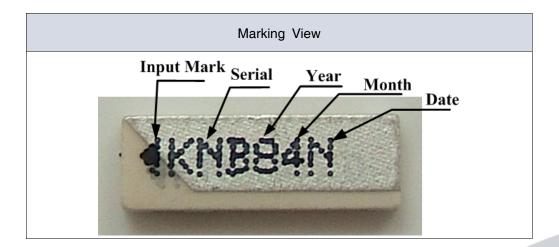
12.2 Lot number notation

① Year : 7 - 2007 ····

2 Month: 1 - January, 2 - February · · 9 - September, A - October, B - November · ·

③ Date : 1 - 1st , 2 - 2nd ···· A - 10th, B - 11th ····

12.3 Marking





- 1 Input Signal
- ② Serial
- ③ Year : 1 2001, 2 2002, ···· 7 2007 ····
- 4 Month: 1 January, 2 February · · 9 September, A October, B November · ·
- ⑤ Date : 1 1st , 2 2nd · · · · A 10th, B 11th · · · ·

12.4 Marking type

Ink marking - Using Black Ink

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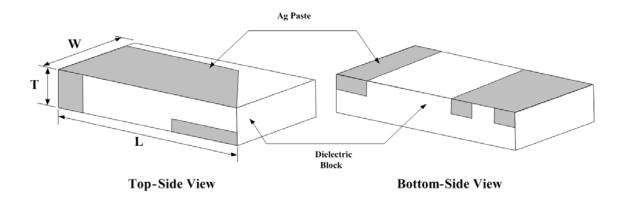


13. Structure and Material

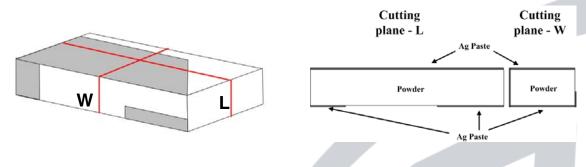
13.1 materialization method

Chip antenna forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

13.2 Struture



13.3 Internal cross section



13.4 Material

ITEM	Material	Maker	Printing pattern SPEC
Dielectric Block	Powder	Fuji	
PATTERN	Ag Paste	DAEJOO	Thickness: TYP 10 ^{µm}
PAD	Ag paste	DAEJOO	Thickness: Min 10/m (TYP 16~20/m)

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14. Attention

14.1 Temperature Condition

	Range of Temperature	Unit
Application temperature	-40 ~ +85	°C
Keeping temperature	-40 ~ +85	°C

14.2 Temperature Test Condition

	Condition	Range of Temperature
Amaliantian tanananatuus	Low	24hr normal action at -75℃
Application temperature	High	24hr normal action at +150°C
		normal action when left for 1000hr at -75°C
Keeping temperature	High	normal action when left for 1000hr at +85℃

 $^{^{\}star}$ Because of the keeping temperature problem, no admission when left over +85 $^{\circ}\mathrm{C}$



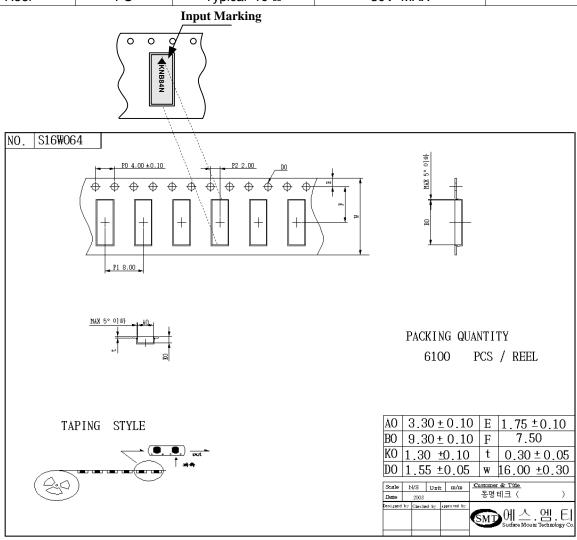
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15. Packing

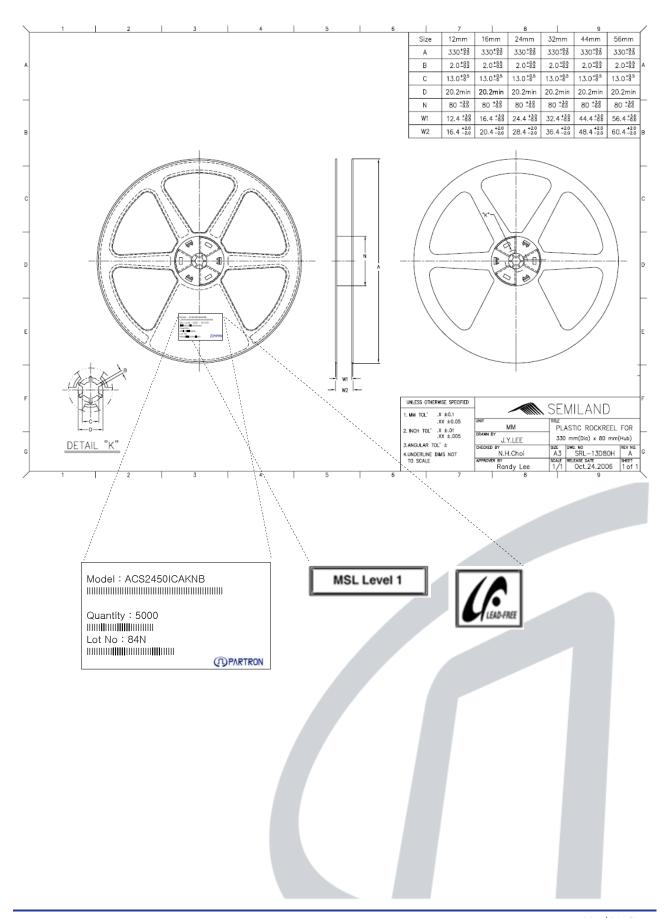
15.1 Carrier/Reel

ITEM	Material	Surface Resistance	electrostatic emission	Packing method
Carrier tape	A-PET	Typical 10 ⁸ Ω	10V MAX	Lloot pyoos
Cover tape	PET	Typical 10 ⁸ Ω	30V MAX	Heat press
Reel	PS	Typical 10°Ω	30V MAX	-





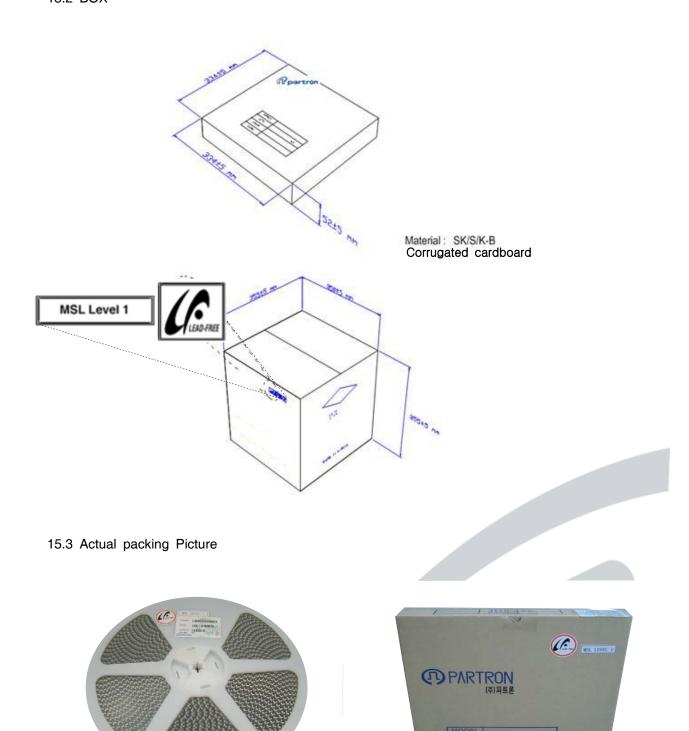




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15.2 BOX



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Internal Box

Ree1





External Box



Reel / Internal Box label



External Box label



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16. Process Control

Product			ls	sued/Revisio	n					Record	By designed	By check	ked By	approved	
CHIP ANTENNA			lssue Revise			Process Control					11				
Input FLOW CHART		Process		Management of Factors					Management of quality						
Materials	prepar ation	Main Process	name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action	
Ceramic POWDER		\Diamond	Import Inspection						shrinking rate permittivity	refer to Guide Sheet	Micrometer Network	10ea/L0T	C/sheet	Return	
POWDER lubricant			powder	Mixer					mixing	POWDER lubricant	Scale	PER MIXING	-	Exhaust	
			Shaping	Press	pressure Mold Condition	refer to Guide Sheet	Per LOT 1/day	parameter C/SHEET	dimension weight density aspect	refer to Guide Sheet	Micrometer scale Calculated Visual	5/100EA 10ea/lot	LOT CARD	Exhaust	
			Plasticity	Plasticity Hole	SETTER Outside Temperature PROFILE	refer to Guide Sheet	all 2/day 1/month	C/sheet							
		\Diamond	Block						wide length shape	refer to Guide Sheet	Micrometer Calipers Visual Inspection	20ea/L0T 20ea/L0T all	C/sheet	Exhaust	
AG PASTE			SIDE1 PAD Printing	Printer screen	Squeeze velocity/presure SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework	
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework	

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	Product			Issued/Revision							Record	By designed	By chec	ked By	approved	
СНІ	CHIP ANTENNA		Issu Revis		04.04.06 05.04.03		Process Control				PRCP-C0	01				
FLOW CHART		Process		M	Management of Factors					Management of quality						
Input Materials			Equipment Name	Checked		Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action		
AG PASTE			SIDE 2 PAD Printing	Printer screen	Sque velocity/ SN/	presure	refer to Guide Sheet	1/day	_	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework	
			Dry	Dryer Dry Jig	Temper Belt		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework	
			Baking	Baking Hole mesh net	Temper Belt		refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework	
AG PASTE			TOP printing	Printer screen	Sque velocity/ SN/	eze presure \P	refer to Guide Sheet	1/day	-	PATTERN dimension	refer to Guide Sheet	measure	10ea/3Jig	c/sheet	Rework	
			Dry	Dryer Dry Jig	Temper Belt s		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework	
AG PASTE			BOTTOM PAD Printing	printer screen	Sque velocity/ SN/	eze presure P	refer to Guide Sheet	1/day	-	PATTERN dimension	refer to Guide Sheet	measure Microscope	10ea/3Jig	c/sheet	Rework	

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Product			lss	Issued/Revision								By designed	By chec	ked By	approved			
CHIP ANTENNA		IA	Issued Revised	Issued 04.04.06 Revised 05.04.03		Process Control				PRCP-C0	01							
Input FLOW CHART			Process	Management of Factors							Management of quality							
Materials		ain cess	name	Fauinment		ked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action			
			Dry	Dryer Dry Jig	Tempera Belt s		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot car	d Rework			
			Baking	Baking Hole mesh net	Tempera Belt s		refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot care	Exhaust Rework			
	<) i	aspect nspection							aspect	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot care	d Exhaust repair			
			MARKING	Marking Machine						marking	Reference SPL	Visual Inspection	all	Lot care production diary				
	<	>	Electrical maracteristic	NETWORK Inspection Jig	proofre Condit		refer to Guide Sheet	1/2hour	C/sheet	Electrical Characteristic	refer to Guide Sheet	Network	all	Lot care				
) ii	aspect nspection							aspect dimension	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot care production diary				
Carrier cover reel			Taping							Quantity Direction aspect	refer to Guide Sheet	Manua I	all	Lot care				
			shipper nspection	NETWORK Inspection Jig	proofre Condit		refer to Guide Sheet	1/person	C/sheet	Electrical Characteristic aspect packing	refer to Guide Sheet	Network microscope Visual Inspection	refer to Guide Sheet	Result Paper	return Exhaust			
packing box label			packing	bar code printer						packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	_	Rework			
		>	packing nspection							packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	_	return			

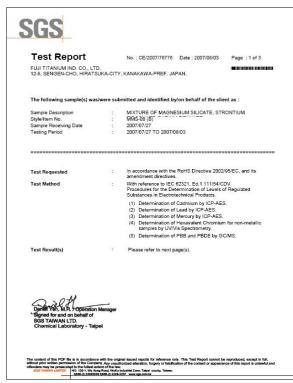
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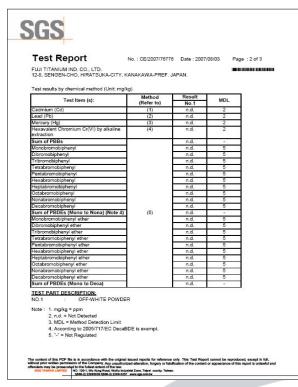


17. RoHS Data

1) Ceramic Powder

Parts Name	White Powder(MMS-08)
Tester Organization	SGS TAIWAN LTD.
Measurement Tester	Please see the 'method' in the test report
Measurement Data	Please see the report under the table









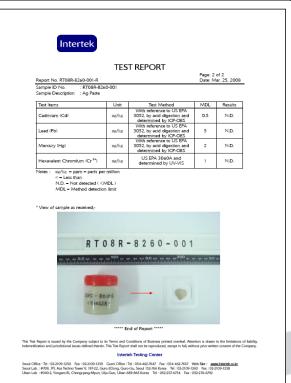
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2) Ag Paste

Parts Name	Silver Paste				
Tester Organization	Intertek				
Measurement Tester	Please see the 'method' in the test report				
Measurement Data	Please see the report under the table				





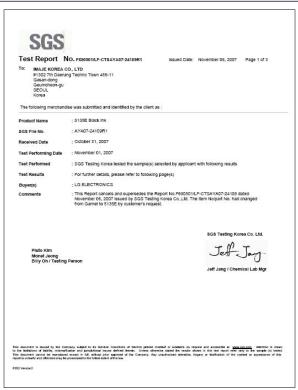


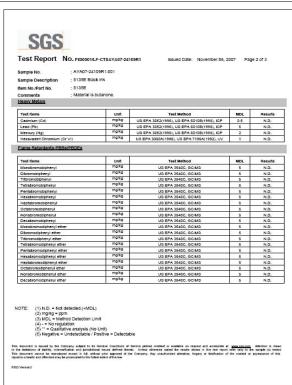
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3) Marking Ink

Parts Name	Black Ink
Tester Organization	SGS Testing KOREA co. Ltd.
Measurement Tester	Please see the 'method' in the test report
Measurement Data	Please see the report under the table







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